L Number	Hits	Search Text	DB	Time stamp
1	2007	(Chip or die) and (adhesive with (heat adj (sink or pipe or spreader or dissipation or dissipate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/28 14:31
3	1	("20010015493").PN.	US-PGPUB	2003/08/28 14:36
2	1038	((Chip or die) and (adhesive with (heat adj (sink or pipe or spreader or dissipation or dissipate)))) and (@ad<19980903)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/28 14:50
4	385	(((Chip or die) and (adhesive with (heat adj (sink or pipe or spreader or dissipation or dissipate)))) and (@ad<19980903)) and (encapsulation or encapsulant or encapsulate or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/28 15:12
5	653	(((Chip or die) and (adhesive with (heat adj (sink or pipe or spreader or dissipation or dissipate)))) and (@ad<19980903)) not ((((Chip or die) and (adhesive with (heat adj (sink or pipe or spreader or dissipation or dissipate)))) and (@ad<19980903)) and (encapsulation or encapsulant or encapsulate or mold))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/28 15:13
-	1	("6455356").PN.	USPAT	2003/08/28 14:28